

Highlights

- Full Digital Output With IIC Interface
- Small size, high reliability package
- Operating Temperature Range:
-20°C to +80°C
- 5 μ A current In Sleep Mode
- Supply Voltage Range: 2.3V-3.6V
- Integrated PGA, 24-bit ADC and DSP
- Integrated ambient temperature
sensor with $\pm 0.2^\circ\text{C}$ (in 0°C -40°C)

Applications

- Human body temperature measurements
- Core temperature measurements
- Heat flux applications

General Description

The J30D is a digital product integrating a heat flux sensor together with a programmable gain amplifier (PGA), a 24 bit ADC and DSP (for calibration/compensation). It also includes an ambient temperature sensor. To store calibration/compensation parameters, a 128 byte EEPROM is available. The all digital IIC interface supports standard and high-speed modes to facilitate the access of various systems. The device can enter low-power sleep mode through instructions and has wake-up function.

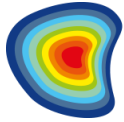
Electrical characteristics

($V_{CC} = 3.3V$, $T_A = +25^{\circ}C$, PGA Gain = 64, unless otherwise noted.)

Parameter	Symbol	Conditions.	Min.	Typ	Max.	Unit
Supply voltage	V_{CC}		2.3	3.3	3.6	V
Power on reset	V_{CCPOR}			1.77		V
Operating current	I_{VCC}	Default config		700	800	μA
Sleep current	I_{SLEEP}			5		μA
Reference voltage	V_{REF}		1.08	1.1	1.12	V
Reference Voltage Temperature Drift	$V_{REFDRIFT}$			30		ppm/ $^{\circ}C$
PGA Gain	G_{PGA}		8		128	
PGA Gain Error	G_{PGAERR}				0.3%	
ADC Resolution	ADC_{RES}			24		Bits
Effective Resolution	ADC_{ENOB}			16		Bits
Oversampling	OSR		128		16384	
EEPROM Programming voltage	V_{EEP}		2.3		3.6	V
EEPROM Programming time	T_{EEP}			1.2	1.92	S
EEPROM Programming cycles	C_{EEP}			10k		
I2C Frequency	F_{SCLK}				400	kHz
Operating temperature	T_{OP}		-20		80	$^{\circ}C$

CAUTION: These devices are sensitive to electrostatic discharge; follow proper IC Handling Procedures.

Heat-flux sensor characteristics



Parameter	Min.	Typ	Max.	Unit
Range	(+/-) 4.1		(+/-) 90	mW/cm ²
Linearity (r ²)	0.9999			-
Repeatability			0.24	mW/cm ²
Relative accuracy		5.4	8.5	% (FS)
Absolute accuracy		4.8	7.6	mW/cm ²

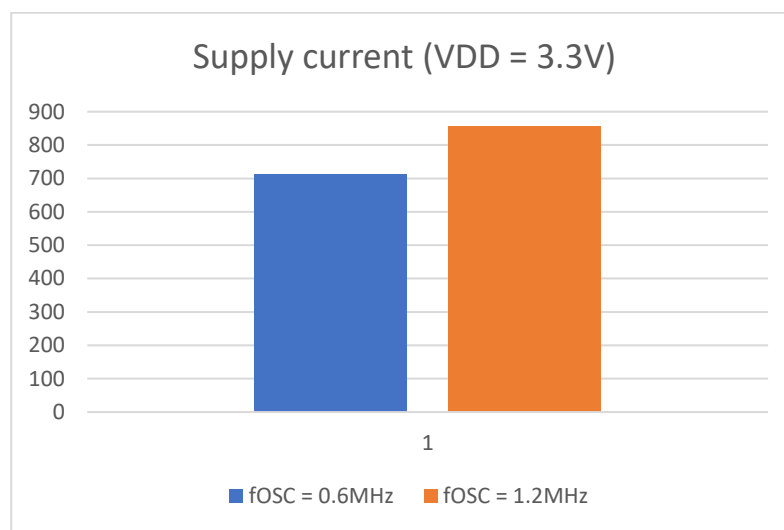
Temperature sensor characteristics

Parameter	Min.	Typ	Max.	Unit
Absolute accuracy	- 0.2		0.2	°C

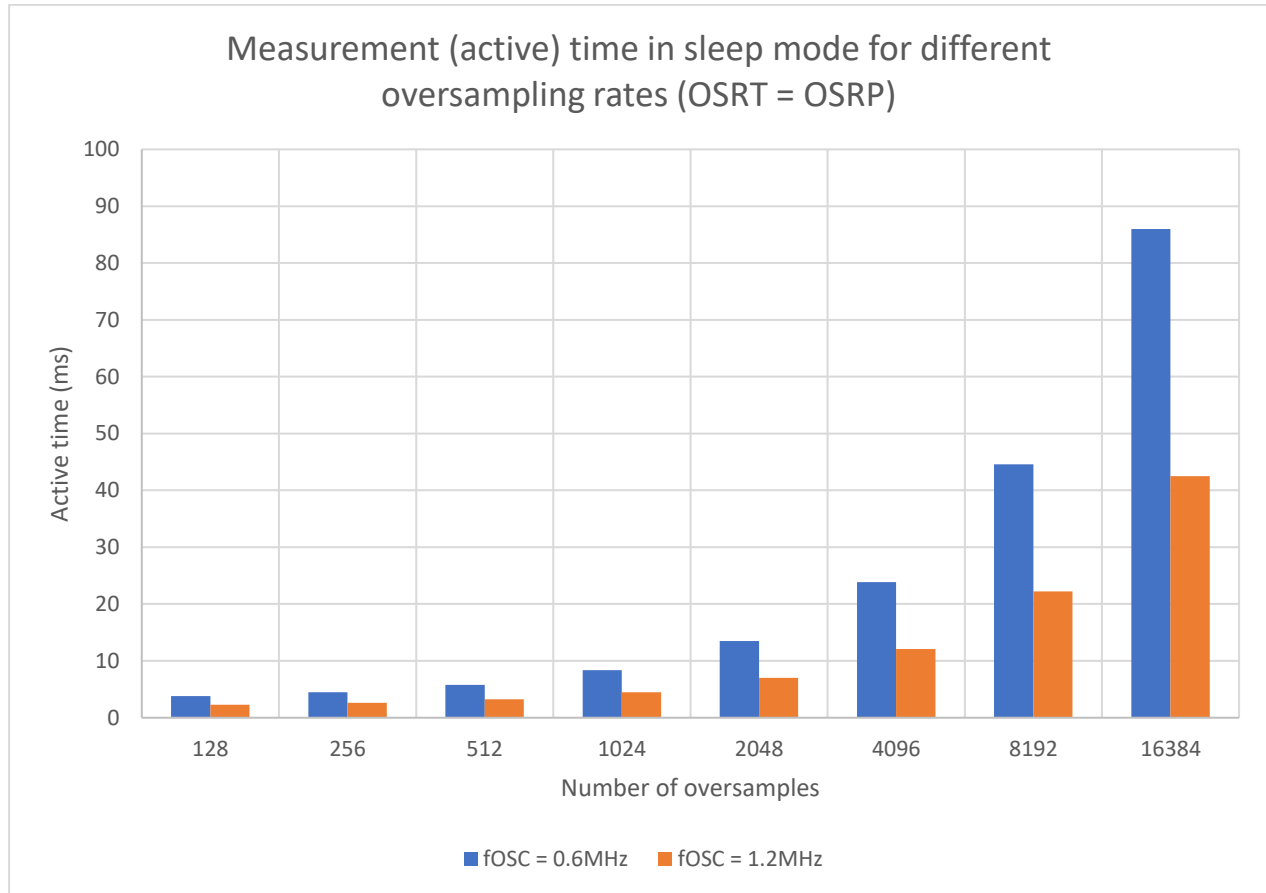
Supply current characteristics

The amount of current a device consumes depends on several factors, such as the voltage it's operating at, the surrounding temperature, the load on its input/output pins, how the device is configured through its software, the frequencies at which it operates, and how often the I/O pins are switched on and off.

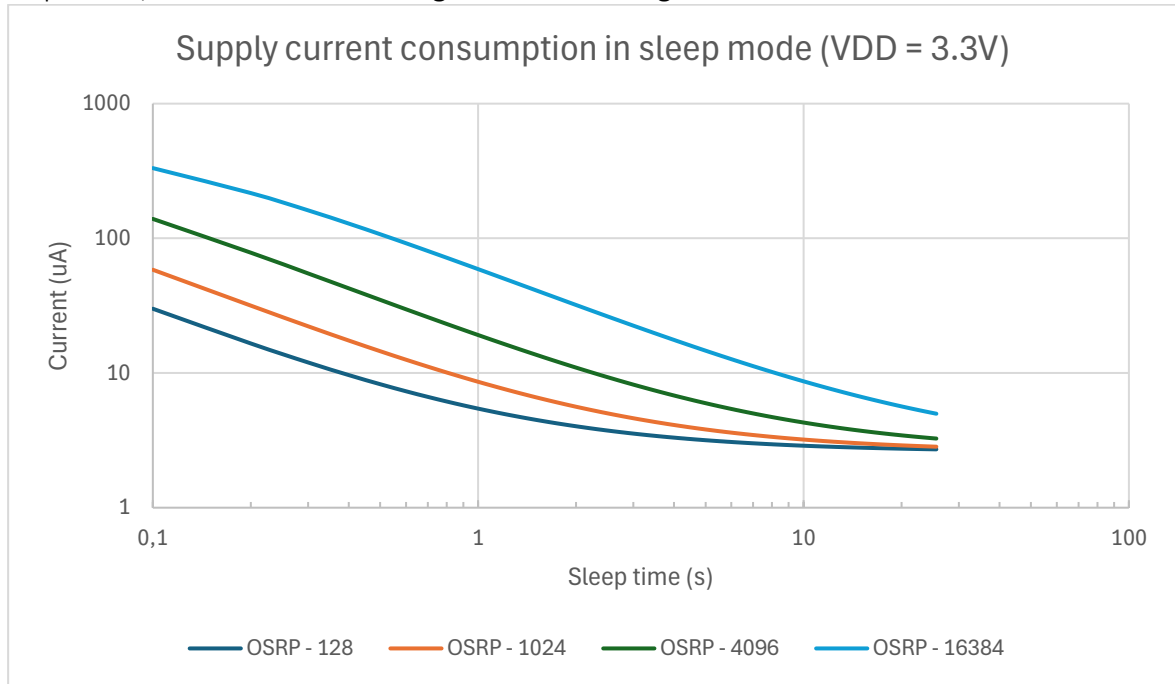
In run mode, the device is always awake and continuously updates the registers as often as possible. The major parameter affecting current consumption in run mode is f_{osc} setting.



In sleep mode, other parameters also come into consideration, such as oversampling rate. The more oversampling, the better signal to noise ratio, but longer measurement times and hence longer active time and increased current consumption.

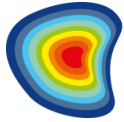


So in sleep mode, different OSRP/OSRT gives the following:

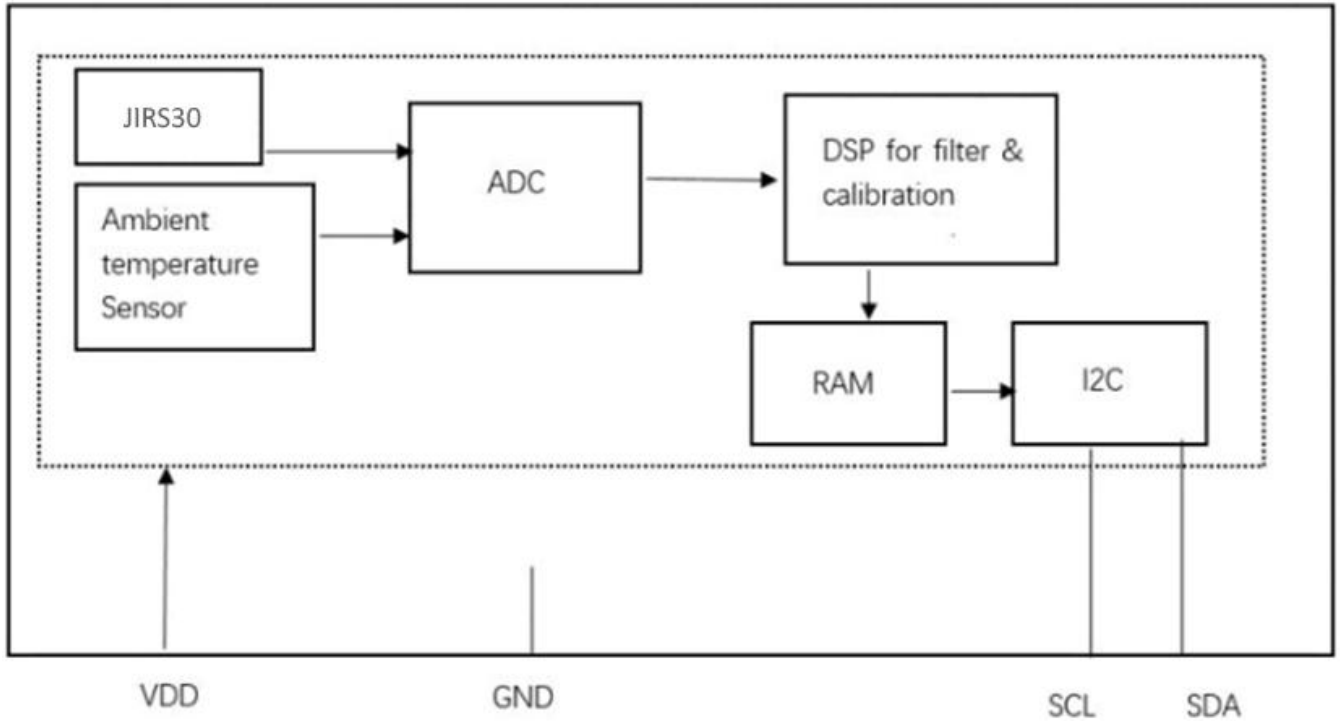


Please note that sleep time (register 0x31) does not consider the actual measurement time.

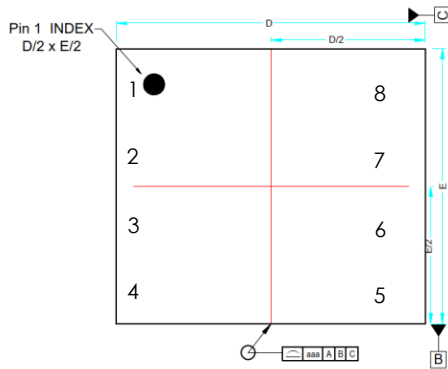
If we use a OSRP = 16384, measurement time will be ~86ms. Setting sleep time to 0x00 = 100ms, the device will measure for 86ms, sleep for 100ms and then repeat.



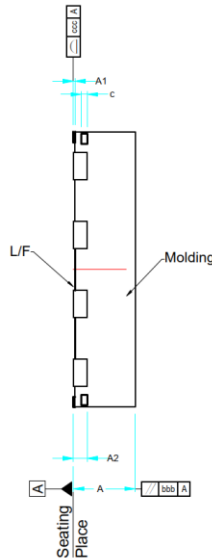
Block Diagram



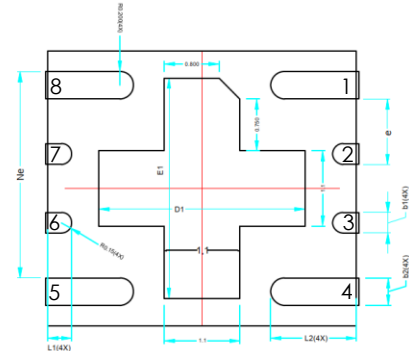
Pin Definitions and Outline



Top View



Side View

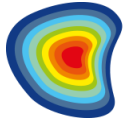


Bottom View

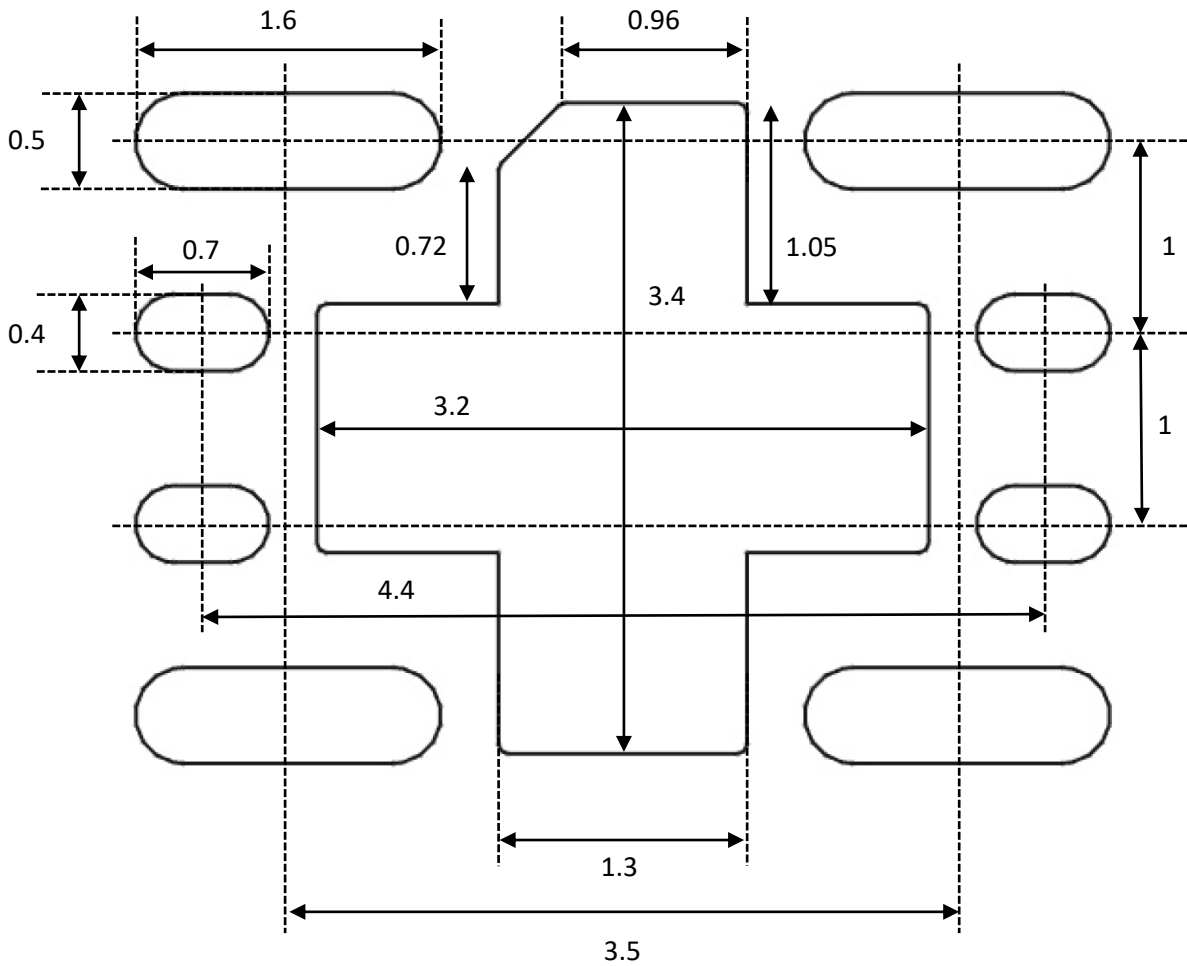
Dimensional tolerances							
unit: mm							
Ref.	MIN	NOR	MAX	Ref.	MIN	NOR	MAX
A	0.80	0.85	0.90	D1	2.90	3.00	3.10
A1	0	0.02	0.05	E1	3.10	3.20	3.30
0.20 BCS				L1	0.3	0.35	0.4
1.00 BCS				b1/b2	0.25/0.35	0.30/0.4	0.35/0.45
e				c	0.0800	0.0900	0.1000
L2	1.2	1.25	1.3				
3.00 BCS				aaa	0.05		
Ne				bbb	0.10		
D	4.40	4.50	4.60	ccc	0.10		
E	3.90	4.00	4.10	ddd	0.08		

DFN4.00X4.50-6L Package Outline Dimension						
TITLE						
Mold Cap Thickness	0.7000	Dwg No	ECM-PD-DFN4.00X4.50-6L-P1.010.90-P1-001-A0			
L/F Thickness	0.203 ± 0.08	Surface Finish	Tin			
Package	6L-DFN4.00X4.50	Sheet	1 OF 1	Scale	1:1	
Dimensions in millimeters tolerances unless otherwise specified XX-0.10 / .XXK-0.040			Third angle projection			

Symbol	Pin	Pin Type	Description
-	1	NC	Do not connect
VDD	2	P	Power supply input pin, it should connect a 100nF to 1.0uF ceramic cap at least to ground.
GND	3	P	Ground
-	4	NC	Do not connect
-	5	NC	Do not connect
SCL	6	I	I2C serial clock input, internally pull up by 500K resistor
SDA	7	I/O	I2C serial data input/output, internally pull up by 500K resistor
-	8	NC	Do not connect



Recommended land pattern



All dimension are in millimeters

Important revision change

The asic used inside J30D has 2 input channels. The very early samples (no revision) during 2025 used channel 2. Components acquired after November 2025 use channel 1. Production units will contain revision information (1 and above).

Communication Interface

I2C

The I2C bus uses SCL and SDA as signal lines. Both of these lines are connected to VCC through a pull-up resistor, and both remain high when not communicating. The IIC device address of J30D can be configured through Chip_Address of register 0x92, and the IIC wildcard 7-bit address is 0x7F. The read data register is polled directly at the time of high-rate reading, and the drdy status bit is read first and then the data register is read when reading at low rate.

I2C Wildcard address:

A7	A6	A5	A4	A3	A2	A1	W/R
1	1	1	1	1	1	1	0/1

The IIC communication protocol has special start (S) and termination (P) conditions. When SCL is at a high level, the falling edge of SDA marks the beginning of data transmission. The IIC master device sends the address (7 bits) of the slave device and the read/write control bit in turn. When the slave device recognizes this address, it generates a response signal and pulls SDA low in the ninth cycle. After getting the response from the slave, the master device continues to send the 8-bit register address and continues to send or read data after getting the response. SCL is at high level, SDA has a rising edge action to mark the end of IIC communication. In addition to the start and end flags, the data transmitted by SDA must remain stable when SCL is high. The value transmitted by SDA can be changed when SCL is low. All data transmission in IIC communication takes 8 bits as the basic unit. After every 8 bits of data transmission, a response signal is required to keep the transmission going.

I2C Timing diagram and characteristics

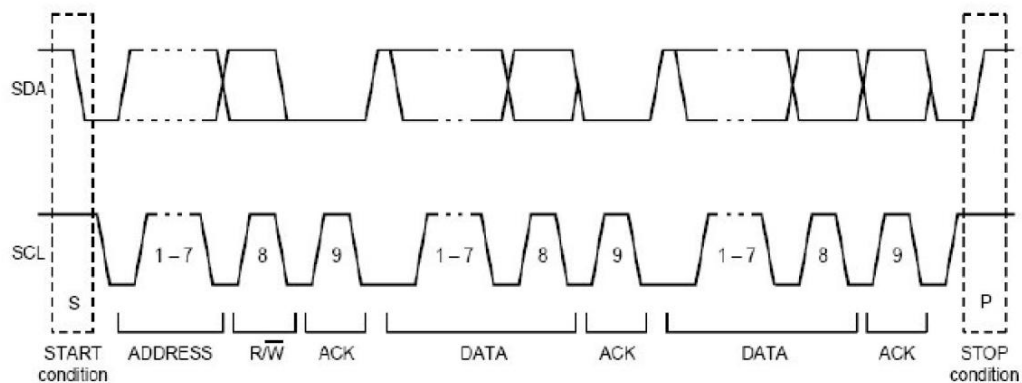
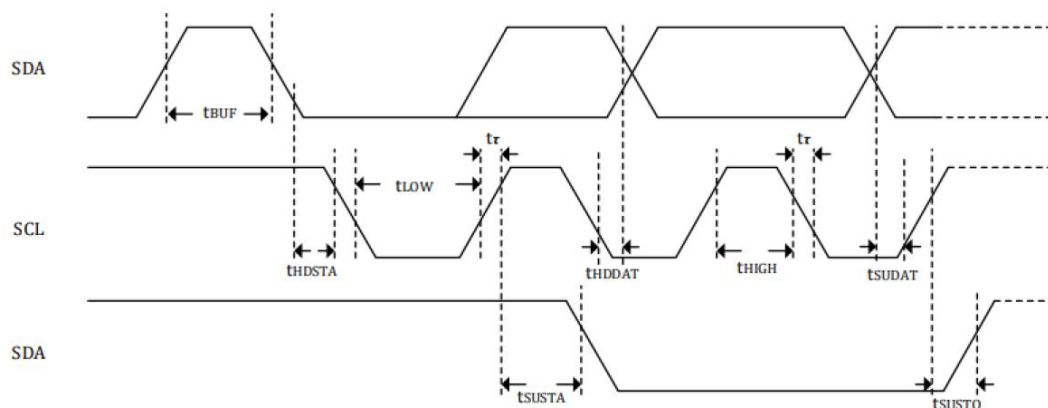
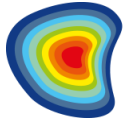


Figure 6.10 IIC Protocol





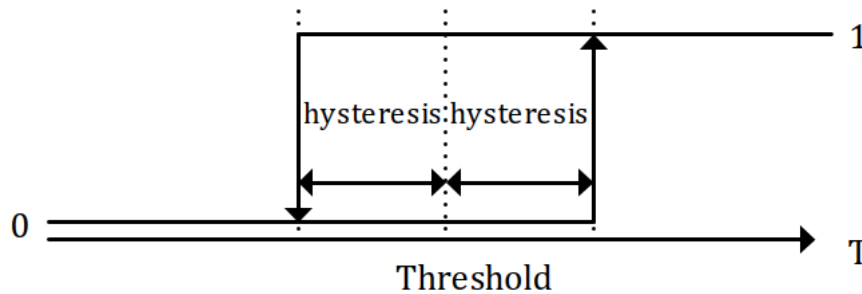
<i>Mar</i>	<i>Parameter</i>		<i>Min</i>	<i>Max</i>	<i>Unit</i>
f_{BsclB}	Clock Frequency			400	kHz
t_{BLOWB}	Clock Low Pulse Sustain Time		1.3		us
t_{BHIGHB}	Clock High Pulse Sustain Time		0.6		us
t_{BSUDATB}	SDA Establishment Time		0.1		us
t_{BHDDATB}	SDA Hold Time		0.0		us
t_{BSUSTAB}	Build Time at Each Start		0.6		us
t_{BHDSTAB}	Start Condition Hold Time		0.6		us
t_{BSUSTOB}	Stop Time Build Time		0.6		us
t_{BBUFB}	Time between Two Communications		1.3		us

PWM

Its not recommended to use PWM mode.

Relay/INT

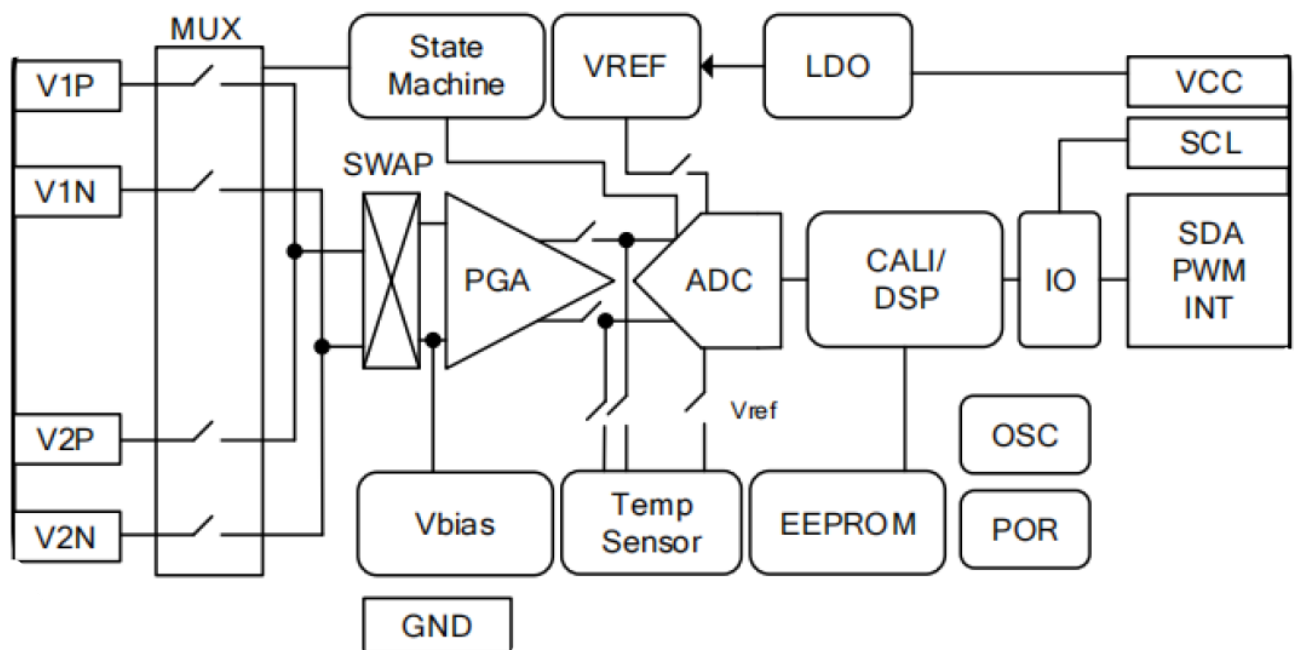
Relay/INT is multiplexed with the SDA pin, and SCL remains high. Relay output takes effect in normal mode, and INT output takes effect in sleep mode. In Normal mode, the default configuration is $T_{o1cal} \geq \text{threshold} + \text{hysteresis}$, Relay output is high; $T_{o1cal} \leq \text{threshold} - \text{hysteresis}$, Relay output is low. Configurable Relay output polarity.



In Sleep mode, combined with the channel combination, see whether To1cal's ADC raw data is compared or To1cal and To2cal are compared with the same threshold in order. If one meets the interrupt condition, the interrupt can be triggered. The register can be configured to be higher than the set threshold to trigger the interrupt or low Trigger an interrupt at the set threshold. The default configuration INT is continuously high, and when the interrupt is triggered, it is pulled low, and returns to high after 50ms.

Function Description

J30D contains a is a highly integrated chip for voltage output sensor, such as thermopile, gas sensor. It supports up to two-channel differential inputs and consists of four parts: analog front-end module, built-in DSP and digital control logic, power supply and high-precision internal clock source, and communication interface circuit. The block diagram is shown in below.



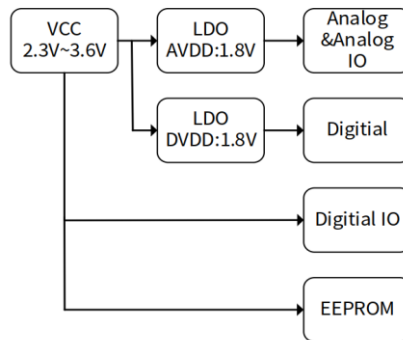
The analog front-end module includes a signal acquisition channel composed of instrument PGA and 24-bit sigma-delta ADC, and a built-in temperature sensor to collect sensor signals and temperature with high precision.

Built-in DSP and digital control logic module includes control logic, built-in DSP, register table, EEPROM, etc. Based on the built-in DSP, the sensor calibration algorithm can calibrate the sensor's zero point and sensitivity below the second order temperature drift and up to the third order nonlinearity.

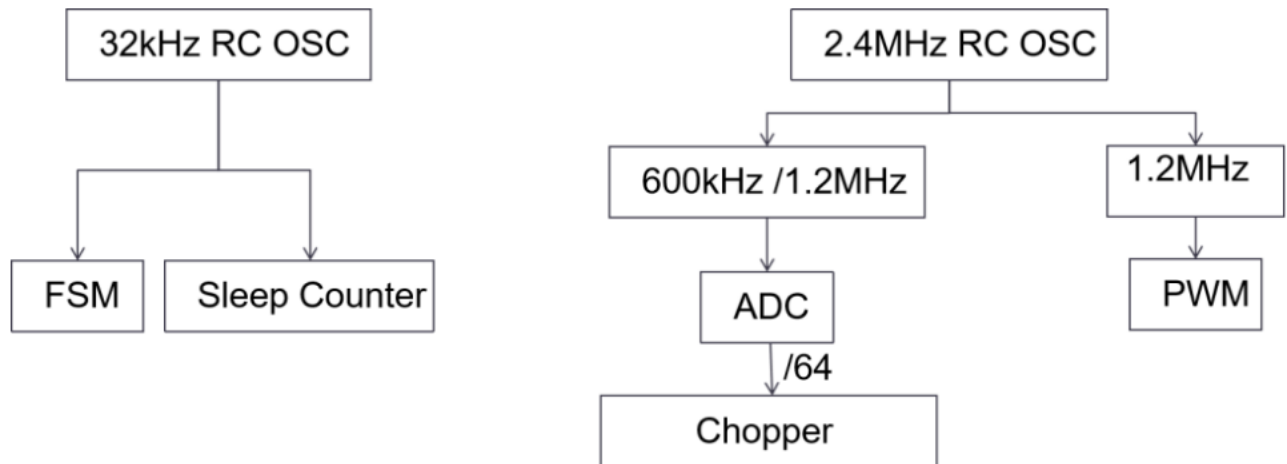
The chip configuration parameters, sensor calibration coefficients, and 25°C thermopile sensor V-T table are stored in 128 bytes of EEPROM. J30D supports three digital interface modes at the same time: IIC, PWM (single bus), INT or Relay output.

Power supply and Clock Module

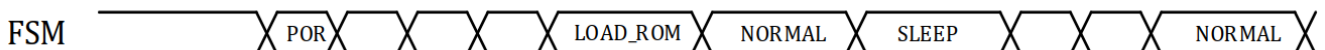
J30D supports 2.3V to 3.6V VCC power supply input, built-in LDO converts VCC into 1.8V to supply power for analog and digital circuits. DVDD power supply is reserved in sleep mode, and the typical current is as low as 5uA. AVDD and DVDD can work after waiting 252us for VCC power supply. The overall power distribution is shown below.



J30D has two clock sources, one is a low-frequency clock of 32kHz, and the other is a high-frequency clock of 600kHz or 1.2MHz. The system clock is shown in the following figure.



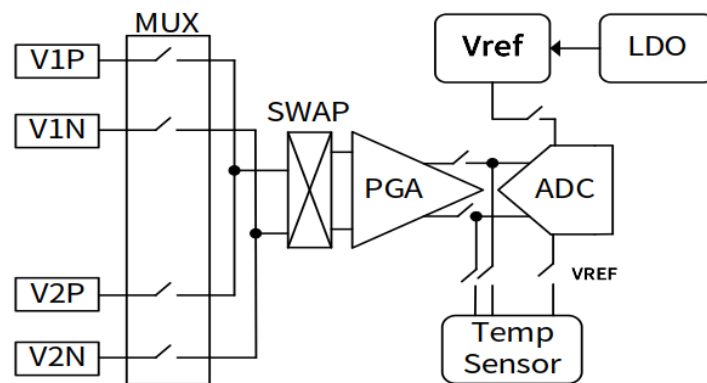
Meanwhile, based on the working state machine of the system, as shown in the below figure, it is recommended to wait for 2ms after powering on (waiting for POR and EEPROM to load) before proceeding with IIC operation. During the operation of the state machine FSM, it is not recommended to manipulate registers. It is recommended to configure registers in the IDLE state.



Main Signal Chain

The J30D signal measurement channel is composed of an input gate circuit MUX, an instrument-level PGA, a 24-bit high-precision Sigma-Delta ADC, and a digital filter.

J30D has two sets of MUX: PGA input MUX and ADC input MUX. The PGA input MUX is used to switch the CH1 and CH2 channels of the thermopile, and the ADC input MUX is used to switch the PGA output and the internal temperature sensor output. When switching to the internal temperature sensor, the reference voltage generated by the temperature sensor itself is used. The Input Swap switch can be used alone to swap the input polarity.



The J30D uses a high-impedance input three-op-amp instrumentation operational amplifier with chopping to reduce the input offset voltage and control the input leakage current below 200pA. Its gain range includes 8x, 12x, 16x, 32x, 48x, 64x, 96x, 128x. 64x is recommended for human body temperature measurement applications, and 8x is recommended for industrial applications.

PGA is a differential input and differential output structure. The output voltage can be expressed by the following expression:

$$\begin{aligned} V_{P_PGA} &= V_{CMin} + GAIN_PGA * V_{Din} / 2 \\ V_{N_PGA} &= V_{CMin} - GAIN_PGA * V_{Din} / 2 \end{aligned}$$

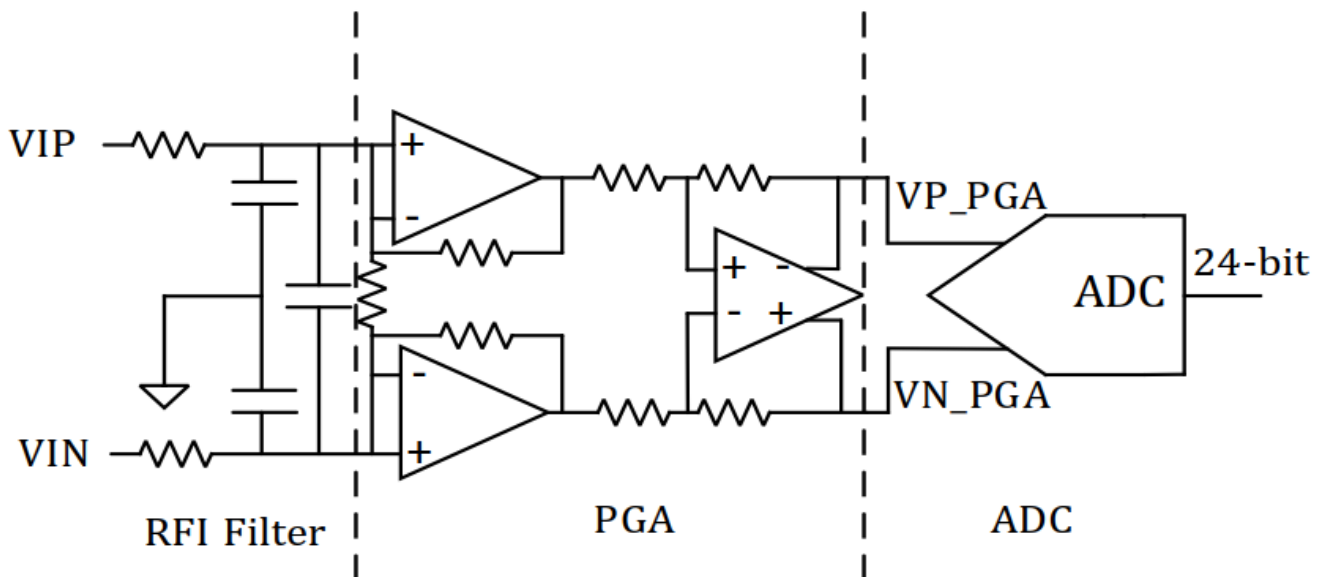
V_{CMin} and V_{Din} are the common mode level and differential mode level of PGA input respectively. In order to avoid the saturation of the PGA's op amp output and the introduction of large errors, both V_{P_PGA} and V_{N_PGA} need to satisfy the following expressions:

$$AGND + 0.3V < V_{P(N)_PGA} < AVDD - 0.3V$$

It can be obtained from the above expression that the input common-mode voltage needs to meet the following relationship:

$$AGND + 0.3V + GAIN_PGA * VDin(max)/2 < V_{CMin} < AVDD - 0.3V - GAIN_PGA * V_{din(max)}/2$$

Considering the inconsistency of sensor output, temperature drift, etc., it is recommended to choose a suitable GAIN_P so that the sensor differential output $VDin(max) < 0.8 * V_{ref}/GAIN_PGA$, the above relationship can be satisfied. In addition, the op amp input of the PGA is a PMOS input, which also needs to satisfy the following expression: $VIP(N) < AVDD - 1V$. J30D has a simple digital potentiometer composed of resistors for thermopile bias. The recommended configuration is $5/16 * AVDD$ ($AVDD=1.8V$).



The ADC performs analog-to-digital conversion on the output of the PGA, and provides a 24-bit digital output after passing through a digital filter. The ADC reference voltage (V_{ref}) is 1.1V, and the allowable differential input signal range is $\pm V_{ref}/GAIN_PGA$.

The expression of ADC output is

$$ADC_{Craw} = \frac{V_{INP} - V_{INN}}{V_{ref}} * GAIN_PGA * 2^{23} = \frac{V_{tp(V)}}{1.1} * GAIN_PGA * 2^{23}$$

The ADCraw of CH1 can be read from the data register DATA (Reg0x22, 0x23, 0x24), and the ADCraw of CH2 can be read from the data register DATA (Reg0x25, 0x26, 0x27). When the sensor is calibrated, the sensor signal can be collected in the bare data mode.

After the ADC is a digital filter, through 'OSR_P' and 'OSR_T' you can set the oversampling rate of the signal chain during sensor signal acquisition and built-in temperature signal acquisition, ranging from 128X to 16384X. The relationship between the effective number of bits and the output noise is:

$$ENOB_{RMS} = 24 - \log_2 (RMS_{ADC})$$

RMS_{ADC} is ADC output noise (LSB).

The relationship between the effective number of bits $ENOB_{RMS}$ and the noise-free number of bits $ENOB_{NF}$ is:

$$ENOB_{NF} = ENOB_{RMS} - 2.7$$

The number of noise-free bits represents the number of bits that the output code has no jitter.

Internal Temperature Sensor

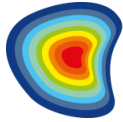
J30D has a built-in CMOS temperature sensor, which can not only measure the ambient temperature, but also provides compensation information for subsequent DSP algorithms. The internal temperature sensor can reach an accuracy of $\pm 0.2^\circ\text{C}$ in the temperature range of $0-40^\circ\text{C}$ (affected by the package wiring). The user does not need to do additional calibration.

The calibrated internal ambient temperature $T_a = \text{ADC_lsb} / 2^{14} (^\circ\text{C})$.

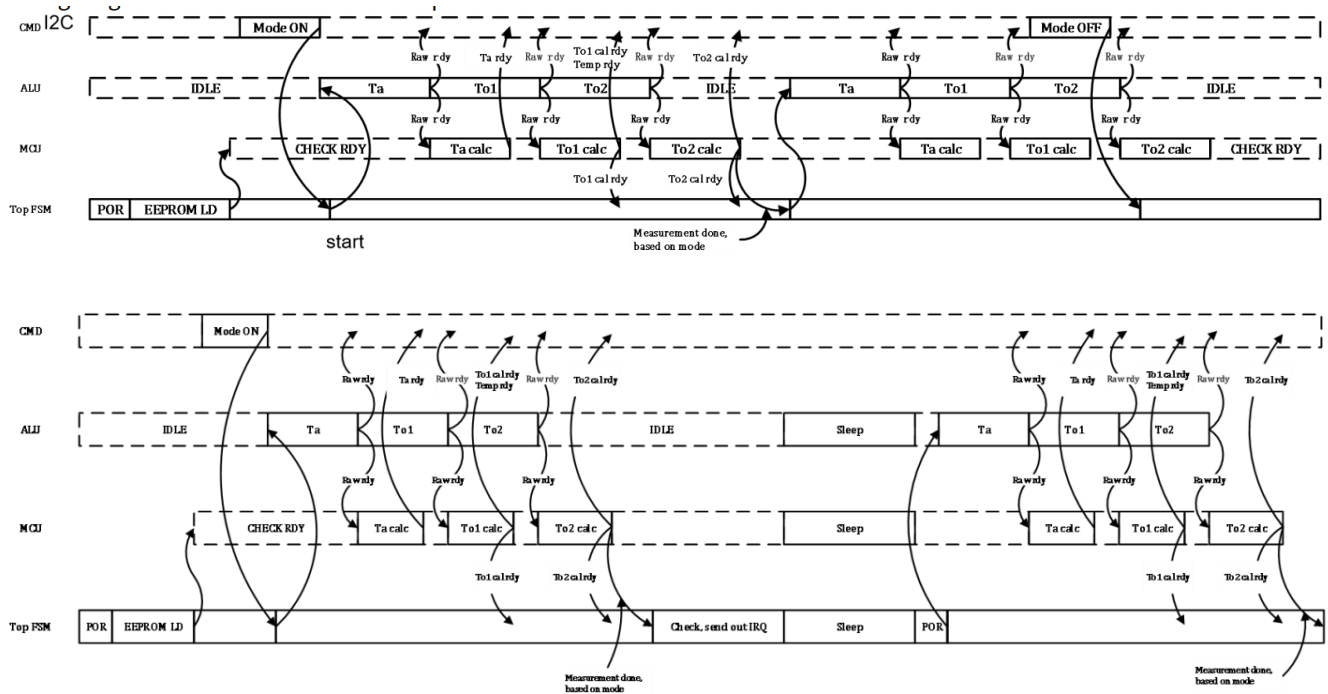
Working Mode

After power-on, J30D can be configured with 0x30 register to realize different working modes, among which sleep_en can switch between normal mode and sleep mode (low power mode), the initial state of mode_sel is IDLE, and the required channel data can be flexibly selected by configuring mode_sel, such as T_a - T_{o1} - T_{o2} is a continuous output of CH1 data once at ambient temperature, once CH2 data combination, and finally configure mode_en to trigger the state machine to work.

Operating Mode	Channel combination	Output
Normal mode	T_a -Ch1 (Single)	IIC/PWM/Relay
	T_a -Ch1- Ch2 (Dual)	IIC
	Ch1- Ch2 (fast dual)	IIC
Sleep mode	T_a -Ch1 (Single)	INT
	T_a -Ch1-Ch2 (Dual)	INT
	Ch1-Ch2 (fast dual)	INT



The figures below shows the timing diagram for Normal and Sleep mode



EEPROM

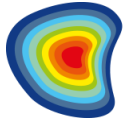
J30DEEPROM is 128 bytes, used to store basic configuration, calibration coefficients and V-T table. The EEPROM default value is 0xFF, and the load time is 240.83us@1.2MHz or 481.67us@600KHz. The total time of erasing and downloading is 120.19ms@1.2MHz or 240.37ms@600KHz. EEPROM will be reloaded after Soft Reset. The content of the EEPROM is automatically loaded into the EEPROM register during the power-on initialization phase. The user's write operation to the EEPROM register will not directly modify the EEPROM value and send a specific EEPROM programming command to the EE_PROG register to take effect.

Write 0x68 to the blow_start register (0x40) to start EEPROM programming and the programming ends with EEPROM_loaded being set to 1.

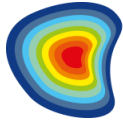
Register Description

Normal Registers

Address	Read/Write	Bit Address	Register Name	Defaults	Describe
0x00 Soft Reset	W	7-6, 4-3, 1-0		2'b0 2'b0 2'b0	Reserved
		5,2	SOFTRESET	1'b0	Write 1 to Bit 5 and Bit 2 to reset entire chip, auto clear to 0 after reset
0x02 Data_ready	R	7-4		4'b0	Reserved
		3	Temp_drdy	1'b0	1'b1: Tobj data after DSP ready
		2	To2_drdy	1'b0	1'b1: To2 data after calibration ready
		1	To1_drdy	1'b0	1'b1: To1 data after calibration ready
		0	Ta_drdy	1'b0	1'b1: Ambient temperature (internal temperature sensor) Ta data after calibration ready
0x03 Data_ready	R	7		1'b0	reserved
		6	To2_raw_drdy	1'b0	1'b1: To2 raw data before calibration ready
		5	To1_raw_drdy	1'b0	1'b1: To1 raw data before calibration ready
		4	Ta_raw_drdy	1'b0	1'b1: Ambient temperature (internal temperature sensor) Ta raw data before calibration ready
		3-0		4'b0	reserved
0x04 error_code	R	7-2		6'b0	reserved
		1	EEPROM_loaded	1'b0	1'b1: EEPROM loaded
		0		1'b0	reserved
0x10 DATA1_MSB	R	7-0	data1_out<23:16>	8'b0	Object temp out Tobj after DSP and IIR filter, 2's complement. DATA1/2 ¹⁴ (°C)
0x11 DATA1_CSB	R	7-0	data1_out<15:8>	8'b0	



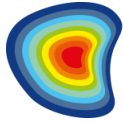
0x12 DATA1_LSB	R	7-0	data1_out<7:0>	8'b0	
0x16 TEMP_MSB	R	7-0	temp_value <23:16>		Ambient temp out (internal temperature sensor) Ta data after calibration, 2's complement. TEMP/2 ¹⁴ (°C)
0x17 TEMP_CSB	R	7-0	temp_value <15:8>		
0x18 TEMP_LSB	R	7-0	temp_value<7:0>		
0x19 DATA1_CAL_MSB	R	7-0	data1_cal_out <23:16>		Channel 1 To1 data after calibration, 2's complement. Vtp data DATA1/2 ¹⁶ (±128mV) DATA1/2 ¹⁹ (±16mV)
0x1A DATA1_CAL_CSB	R	7-0	data1_cal_out <15:8>		
0x1B DATA1_CAL_LSB	R	7-0	data1_cal_out <7:0>		
0x1C DATA2_CAL_MSB	R	7-0	data2_cal_out <23:16>		Channel 2 To2 data after calibration, 2's complement. Vtp data DATA2/2 ¹⁶ (±128mV) DATA2/2 ¹⁹ (±16mV)
0x1D DATA2_CAL_CSB	R	7-0	data2_cal_out <15:8>		
0x1E DATA2_CAL_LSB	R	7-0	data2_cal_out <7:0>		
0x22 DATA1_RAW_MSB	R	7-0	data1_raw_out <23:16>		Channel 1 To1 raw data before calibration, 2's complement. ADCraw
0x23 DATA1_RAW_CSB	R	7-0	data1_raw_out <15:8>		
0x24 DATA1_RAW_LSB	R	7-0	data1_raw_out <7:0>		
0x25 DATA2_RAW_MSB	R	7-0	data2_raw_out <23:16>		Channel 2 To2 raw data before calibration, 2's complement. ADCraw
0x26 DATA2_RAW_CSB	R	7-0	data2_raw_out <15:8>		
0x27 DATA2_RAW_LSB	R	7-0	data2_raw_out <7:0>		
0x28 TEMP_RAW_MSB	R	7-0	temp_raw_value <23:16>		Ambient temperature(internal temperature sensor) Ta raw data before calibration, 2's complement.
0x29 TEMP_RAW_CSB	R	7-0	temp_raw_value <15:8>		



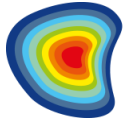
0x2A TEMP_RAW_LSB	R	7-0	temp_raw_value <7:0>		ADCrAw
0x30 CMD	RW	7-6		2'b0	reserved
		5	sleep_en	1'b0	1'b1 enter sleep mode; 1'b0 exit sleep mode.
		4	clk_mode	1'b0	1'b0 600KHz; 1'b1 1.2MHz
		3	mode_en	1'b0	1'b1 start FSM
		2-0	mode_sel<2:0>	3'b0	3'b000/001: single-channel continuous conversion (Ta-To1); 3'b010: dual channels continuous conversion (Ta-To1- To2) 3'b011: fast-dual channel mode (To1-To2)
0x31 Sleep_time	RW	7-0	Sleep_time<7:0>	8'b0	0x00: 100ms 0x01: 200ms 0x02: 300ms ... 0xFF: 25.6s
0x40 BLOW_start	RW	7-2	Blow_start<5:0>	6'b0	Blow_start<5:0>==6'b011010, to blow EEPROM.
		1-0		2'b0	Reserved, 2'b00: Use auto mode

EEPROM Registers

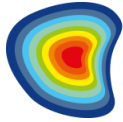
Address	Read/Write	Bit Address	Register Name	Defaults	Describe
0x90 ID0	RW	7-0	ID0<7:0>	EE_0	Chip ID0 for customer
0x91 ID1	RW	7-0	ID1<7:0>	EE_1	Chip ID1 for customer
0x92 Chip_Address	RW	7		EE_2	Chip_Address<6:0>: IIC Address 7'h7F is an always effective address
		6-0	Chip_Address <6:0>		
0x93 System_Config_1	RW	7-5	FILT_COEF<2:0>	EE_3	IIR filter coefficient. 3'b000 disable IIR filter; 3'b001 suppress 17% of signal; 3'b010 suppress 25% of signal;



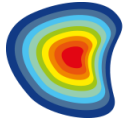
					3'b011 suppress 50% of signal; 3'b100 suppress 63% of signal; 3'b101 suppress 75% of signal; 3'b110 suppress 88% of signal; 3'b111 suppress 94% of signal.
		4-3	output_mode <1:0>		2'b00: IIC, 2'b01: PWM, 2'b10: Relay, 2'b11. IIC. latched after EEPROM loaded. Changes made to this will take effect ONLY IF this value is programmed to EEPROM and then reset the chip.
		2-0	OSR_T<2:0>		OSR for ambient temperature measurement. 000:512X, 011:1024X, 010:2048X, 011:4096X, 100:128X, 101:256X, 110:110:8192X, 111:16384X.
0x94 System_Config_2	RW	7	adc_dither_en	EE_4	1'b1 enable ADC internal dither
		6	SERIAL_filter_en		1'b1 enable IIC input deglitch filter
		5-4	PGA_PWR<1:0>		Reserved Trade-off between power and noise.
		3	Relay_OUT_Polari ty		1'b0: output 1 when higher than threshold. 1'b1: output 1 when lower than threshold
		2	SLEEP_OUT_Polar ity		(IIC) Always output 1 when not trigger INT, output 0 when trigger INT, when trigger INT, leave SLEEP_MODE. 1'b0: trigger INT when temp is higher than threshold; default 1'b1: trigger INT when temp is lower than threshold.
		1	VT_SCALE		1'b0: ±16mV; 1'b1: ±128mV
		0	input_swap		Set to 1 in case Thermopile sensor +/- bond to NSA3300 in reverse manner
0x95 Sensor_Channel1_Conf ig	RW	7		EE_5	reserved
		6			reserved
		5-3	Gain_P<2:0>		000: gain=8, 001:gian=12, 010:gain=16, 011:gain=32,



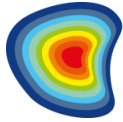
					100:gain=48, 101:gain=64, 110:gain=96, 111:gain=128
		2-0	OSR_P<2:0>		000:512X, 011:1024X, 010:2048X, 011:4096X, 100:128X, 101:256X, 110:110:8192X, 111:16384X.
0x96 Sensor_Channel2_Config	RW	7		EE_6	reserved
		6			reserved
		5-3	Gain_P<2:0>		000: gain=8, 001:gain=12, 010:gain=16, 011:gain=32, 100:gain=48, 101:gain=64, 110:gain=96, 111:gain=128
		2-0	OSR_P<2:0>		000:512X, 011:1024X, 010:2048X, 011:4096X, 100:128X, 101:256X, 110:110:8192X, 111:16384X.
0x97 BPS_CONFIG	RW	7-4		EE_7	reserved
		3-0	RES_DAC<3:0>		4'b1101 5/16*AVDD (suggested)
0x9F Tomax_1	RW	7-0		EE_15	Tomax_1: To_max<15:8> Tomax_2:
0xA0 Tomax_2	RW	7-0		EE_16	To_max<7:0> To_max<15:0> /64 mapping to real setting maximum °C
0xA1 Tomin_1	RW	7-0		EE_17	Tomin_1: To_min<15:8> Tomin_2: To_min<7:0>
0xA2 Tomin_2	RW	7-0		EE_18	To_min<15:0> /64 mapping to real setting minimum °C
0xA3 PWMCTRL	RW	7-0		EE_19	period of PWM output, where 1x PWM period stands for ~1706us 0: 256x; 1: 1x; 2: 2x, ..., 255: 255x.
0xA4 Emissivity_1	RW	7-0		EE_20	Emissivity range 0.05 ~ 1 Emissivity_1: Emissivity<15:8>
0xA5 Emissivity_2	RW	7-0		EE_21	Emissivity_2: Emissivity<7:0> LSB=2 ¹⁵ 2's complement, i.e. 0.05*2 ¹⁵ -1
0xA6 TCsens_1	RW	7-0		EE_22	TCsens range-0.5%/K ~ +0.5%/K TCsens_1: TCsens<15:8>
0xA7 TCsens_2	RW	7-0		EE_23	TCsens_2: TCsens<7:0> LSB=2 ²²



					i.e. 0.1%/K: 0.001*2 ²²
0xA8 T_threshold_1	RW	7-0		EE_24	Relay mode threshold T_threshold_1: T_threshold<15:8>
0xA9 T_threshold_2	RW	7-0		EE_25	T_threshold_2: T_threshold<7:0> LSB=mV*2 ⁸
0xAA T_hyst_1	RW	7-0		EE_26	Relay mode hysteresis T_hyst_1: T_hyst<15:8>
0xAB T_hyst_2	RW	7-0		EE_27	T_hyst_2: T_hyst<7:0> LSB=1mV*2 ⁸
0xAC T_threshold_sleep_MSB	RW	7-0		EE_28	Sleep mode INT threshold T_threshold_sleep<15:0> LSB=1mV*2 ⁸
0xAD T_threshold_sleep_LSB	RW	7-0		EE_29	
0xAE CH1_OFF_MSB	RW	7-0		EE_30	Channel1 To1 calibration CH1_OFF<15:0>
0xAF CH1_OFF_LSB	RW	7-0		EE_31	0x7FFF->0.5*Vref=0.5*1.1->vtp= 0.5*1.1/PGAgain
0xB0 CH1_GAIN_MSB	RW	7-0		EE_32	Channel1 To1 calibration CH1_GAIN<15:0>
0xB1 CH1_GAIN_LSB	RW	7-0		EE_33	
0xB2 CH1_KS_MSB	RW	7-0		EE_34	CH1_KS<11:4>
0xB3 CH1_KSS_MSB	RW	7-0		EE_35	CH1_KKS<11:4>
0xB4 CH1_KS_LSB	RW	7-4		EE_36	CH1_KS<3:0>
		3-0			CH1_KSS<3:0>
0xB5 CH2_OFF_MSB	RW	7-0		EE_37	Channel2 To2 calibration CH2_OFF<15:0>
0xB6 CH2_OFF_LSB	RW	7-0		EE_38	



0xB7 CH2_GAIN_MSB	RW	7-0		EE_39	Channel2 To2 calibration CH2_GAIN<15:0>
0xB8 CH2_GAIN_LSB	RW	7-0		EE_40	
0xB9 CH2_KS_MSB	RW	7-0		EE_41	CH2_KS<11:4>
0xBA CH2_KSS_MSB	RW	7-0		EE_42	CH2_KKS<11:4>
0xBB CH2_KS_LSB	RW	7-4		EE_43	CH2_KS<3:0>
		3-0			CH2_KSS<3:0>



Calibration data registers

Address	Register name	Size	Description
0xC0	Production timestamp MSB	uint32	Unix time stamp
0xC1	Production timestamp second byte		
0xC2	Production timestamp third byte		
0xC3	Production timestamp LSB		
0xC4	Unique chip id MSB	uint32	4 byte number unique device id
0xC5	Unique chip id second byte		
0xC6	Unique chip id third byte		
0xC7	Unique chip id LSB		
0xC8	Chip revision	uint8	
0xC9	Lot no MSB	uint16	
0xCA	Lot no LSB		
0xCB	Wafer no MSB	uint16	
0xCC	Wafer no LSB		
0xCD	Sensor offset 1 MSB (m)	U8Q8 Format	$Q = ADC_{RAW} * k - m$
0xCE	Sensor offset 1 LSB (m)		
0xCF	Reserved		
0xD0	Reserved		
0xD1	Sensor gain 1 MSB (k)	U8Q8 Format	$Q = ADC_{RAW} * k - m$
0xD2	Sensor gain 1 LSB (k)		
0xD3	Reserved		
0xD4	Reserved		
0xD5	Sensor offset 2 MSB	U8Q8 Format	Not used
0xD6	Sensor offset 2 LSB		
0xD7	Reserved		
0xD8	Reserved		
0xD9	Sensor gain 2 MSB	U8Q8 Format	Not used
0xDA	Sensor gain 2 LSB		
0xDB	Reserved		
0xDC	Reserved		
0xDD	alpha MSB	U8Q8 Format	Not used
0xDE	alpha LSB		
0xDF – 0xED	Reserved		
0xEE	16-bit CRC MSB		CRC-CCITT (CRC16), POLY: $0x8408 (X^{16} + X^{12} + X^5 + 1)$
0xEF	16-bit CRC LSB		
0xDF – 0xEF	Reserved		

U8Q8 Format

Range: 0 to 255.996 (integer part can range from 0 to 255)

Fractional part can represent values from 0 to just under 1.

Precision: $1/256 = \text{approx } 0.00390625$

MSB represent integer part and LSB fractional part.

ADC_{RAW} corresponds to channel used inside J30D for converting the raw analog sensor data to a voltage.

Regarding CRC, Early samples before Nov 2025 has no production data.

Samples after Nov2025 contains gain/offset1 and production timestamp and UID

Production units (rev1 and higher) contains CRC.

Example code

Please visit https://github.com/JonDeTech/J30D_Reference

Revision history

Date	Description
2025-05-25	Initial version
2025-08-11	Added pin numbering
2025-09-25	Added register description
2025-11-18	Added function description
2025-12-12	Added custom calibration layout Updated package drawing
2026-01-09	Update package drawing
2026-01-13	Update supply current characteristics
2026-01-16	Added land pattern